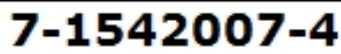


 Live Product Chat US Only
8:30am - 5pm ET, Mon - Fri



 Active

 [Add to Part List](#)

 Always EU RoHS/ELV Compliant (Statement of Compliance)

- Heat Sink
- BGA
- Package Size = 29 [1.142] mm [in]
- For Use With BGA Semiconductor Packages
- Power Air Velocity Thermal Resistance

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Product Drawings:

- [29mm HEATSINK ASSEMBLY](#) (PDF, English)

Catalog Pages/Data Sheets:

- None Available

Product Specifications:

- None Available

Application Specifications:

- None Available

Instruction Sheets:

- None Available

CAD Files:

- None Available

[List all Documents](#)

- Product Line Information

- Line Drawing
- Thermal Resistance Chart

- Tooling

Product Features (Please use the Product Drawing for all design activity)

- Product Type = Heat Sink
- Device Type = BGA
- For Use With = BGA Semiconductor Packages
- Finish = Black Anodize
- Material = Cold-Forged Aluminum
- Comment = Mounting clip does not increase overall heat sink height.; Heat sink assembly includes Three Leg Low Profile Clip, Part Number 1542432-1.

- Heat Sink Type = Pin Fin 1
- Fan Type = No Fan

- Height (mm [in]) = 12.70 [0.500]

- Package Size (mm [in]) = 29 [1.142]
- Flammability Rating = UL 94V-0

- Diameter (mm [in]) = 34.95 [1.376]

- RoHS/ELV Compliance = RoHS compliant, ELV compliant
- Lead Free Solder Processes = Not relevant for lead free process
- RoHS/ELV Compliance History = Always was RoHS compliant

- Brand = Tyco Electronics
- Line = ChipCoolers

When Power (W) is:	And Air Velocity is:	Thermal Resistance (°C) is:
5.0	0 LFM	12.44
5.0	200 LFM	7.13
5.0	400 LFM	5.19
5.0	600 LFM	3.85
5.0	With Fan	3.64
10.0	0 LFM	11.06
10.0	200 LFM	7.11
10.0	400 LFM	5.06
10.0	600 LFM	3.68
10.0	With Fan	3.45
15.0	0 LFM	10.08
15.0	200 LFM	6.93
15.0	400 LFM	4.95
15.0	600 LFM	3.60
15.0	With Fan	3.36